

ABSTRACT

A curable composition comprising (A) a
5 polyfluorodialkenyl compound having at least two alkenyl
radicals, (B) a fluorinated organohydrogensiloxane having at
least two Si-H radicals, (C) a platinum group compound, (D) a
hydrophobic silica powder, and (E) an organosiloxane having a
Si-H radical and a trialkyl or trialkoxy-containing organic
10 radical attached to a silicon atom cures into a product
having improved solvent resistance, chemical resistance, heat
resistance, low-temperature properties, low moisture
permeability and electric properties and exhibiting good
adhesion to a variety of substrates including metals and
15 plastics by brief heating at relatively low temperatures.